



1449 (Modified)

Information Disclosure Statement By Applicant (Use Several Sheets if Necessary)	Atty Docket No. ALTRP096/A1201	Application No.: 10/719,451
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**U.S. Patent Documents**

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
<i>W</i>	A1	6,617,683	09/2003	Lebonheur, <i>et al.</i>			
<i>W</i>	A2	6,504,242	01/2003	Deppisch, <i>et al.</i>			
	A3	6,756,685	06/2004	Tao, Tetsuya			
	A4	6,262,489	07/2001	Koors, <i>et al.</i>			
	A5	6,773,963	08/2004	Houle, Sabina J.			
	A6	5,909,056	06/1999	Mertol, Atila			
	A7	6,091,603	07/2000	Daves, <i>et al.</i>			
	A8	6,472,762	10/2002	Kutlu, Zafer S.			
<i>W</i>	A9	6,744,132	06/2004	Alcoe, <i>et al.</i>			
<i>W</i>	A10	6,103,550	08/2000	Camenforte, <i>et al.</i>			

**Foreign Patent or Published Foreign Patent Application**

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation
							Yes
							No

**Other Documents**

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
<i>J</i>	C1	U.S. Patent Application, Serial No.: 10/849,651 filed May 19, 2004 entitled: <i>Low Stress And Warpage Laminate Flip Chip BGA Package</i>

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.